300mm Fully-Automatic Multifunction Wafer Mounter

RAD-2510F/12Sa

Outline

- Fully-automatic wafer mounter suited for ultra-thin wafer manufacturing, with the following functions:
  - UV irradiation to BG Tape
  - Alignment
  - Wafer mounting
  - BG Tape peeling
- Ability to operate in-line with DISCO Corporation’s DFG8000 series back grinder or DGP8000 series grinder/polisher.
- Corresponds to DBG process.
- Prevents wafer damage by reducing wafer handling frequency down to 4 times “stand-alone,” and 2 times “in-line.”

Options

- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Dicing Tape In-line Pre-cutting
- DBG Process Compatibility
- In-line Operation with DISCO Corporation DFG8000 series or DGP8000 series

Suitable Tapes

- Dicing tape: Adwill D series, G series
- Dicing die bonding tape: Adwill LE Tape

External View

Facility

<table>
<thead>
<tr>
<th>Power Supply</th>
<th>Voltage : AC200 (±10%)</th>
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<tbody>
<tr>
<td></td>
<td>Frequency : 50/60Hz</td>
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<tr>
<td></td>
<td>Phase : 3 phase</td>
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<tr>
<td>Air Supply</td>
<td>Power consumption : 8.0kW (200VAC)</td>
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<td>Air pressure : 0.6-0.8MPa</td>
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<tr>
<td></td>
<td>Air consumption : &gt;800L/min (ANR)</td>
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<tr>
<td>Vacuum Supply</td>
<td>Vacuum pressure : &gt;-80kPa</td>
</tr>
</tbody>
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Applicable Wafer Size

- 200mm, 300mm

Size

- Width : 2,165mm
- Depth : 3,090mm
- Height : 1,800mm
(excluding the signal tower and protruding parts)

Weight

- 3,100kg

UPH

- 45 wafers/hour

The above processing capacity is based on following conditions (“stand-alone”):

- Wafer : 300mm diameter non-polished mirror wafer
- Ring frame : for 300mm wafer
- Dicing tape : G-18 from LINTEC
- Back grinding tape : E-8180HR from LINTEC

Outline

- Applicable Wafer Size
- Weight
- UPH

External View

Unit: mm

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